

N-Channel Enhancement Mode Power MOSFET

Description

The MS6N40 is a N-channel enhancement-mode MOSFET, providing the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost effectiveness. The TO-220 package is universally preferred for all commercial-industrial applications

Features

- BVDSS=650V typically @ Tj=150°C
- Low On Resistance
- · Simple Drive Requirement
- · Low Gate Charge
- · Fast Switching Characteristic
- · RoHS compliant package

Application

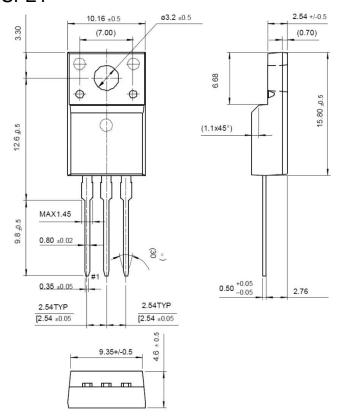
- Adapter
- · Switching Mode Power Supply

Packing & Order Information

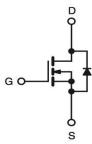
50/Tube; 1,000/Box







Graphic symbol



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings (Tc=25°C unless otherwise specified)				
Symbol	Parameter	Value	Unit	
V_{DSS}	Drain to Source Voltage	400	V	
V_{GS}	Gate to Source Voltage	±30	V	
I _D	Continuous Drain Current (TC=25°C)	5.5	Α	
	Continuous Drain Current (TC=100°C)	3.5		
I_{DM}	Drain Current Pulsed	16.4	A	
E _{AS}	Single Pulsed Avalanche Energy	240	mJ	
E _{AR}	Repetitive Avalanche Energy	10	mJ	
dv/dt	Peak Diode Recovery dv/dt	5.5	V/ns	

Drain current limited by maximum junction temperature



N-Channel Enhancement Mode Power MOSFET

Absolute N	Absolute Maximum Ratings (Tc=25°C unless otherwise specified)					
Symbol	Parameter	Value	Unit			
T _L	TL Maximum Temperature for Soldering @ Lead at 0.125 in(0.318mm) from case for 10 seconds	300	°C			
T _{PKG}	TPKG Maximum Temperature for Soldering @ Package Body for 10 seconds	260	°C			
Б	Total Power Dissipation(@TC = 25 °C) 100 W	100	W			
P_D	Derating Factor above 25 °C	0.8	W/°C			
T _{STG}	Operating Junction Temperature	-55 to +150	°C			
TJ	Storage Temperature	150	°C			

Note:

- 1.Repetitive rating; pulse width limited by maximum junction temperature.
- 2. IAS=4A, VDD=50V, L=8mH, VG=10V, starting TJ=+25°C.
- 3. ISD≤4A, dI/dt≤100A/µs, VDD≤BVDSS, starting TJ=+25°C.

Thermal Cha	Thermal Characteristics					
Symbol	vmbol Parameter		Value			
Symbol		Min.	Тур.	Max.	Units	
$R_{ heta JC}$	Thermal Resistance,Junction-to-Case			1.25	°C/W	
$R_{\theta JA}$	Thermal Resistance,Junction-to-Ambient			62.5	°C/W	

Static Characteristics					
Symbol	Test Conditions	Min	Тур.	Max.	Units
V_{GS}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2.0		4.0	V
*R _{DS(ON)}	$V_{GS} = 10 \text{ V}, I_D = 2.75 \text{ A}$		0.8	1.0	Ω
BV _{DSS}	$V_{GS} = 0 \text{ V}$, $I_D = 250 \mu A$	400			V
$\Delta BV_{DSS}/\Delta T_{J}$	Reference to 25°C, $I_D = 250 \mu A$		0.4		
l	V _{DS} = 400 V, V _{GS} = 0 V			1	uA
I _{DSS}	$V_{DS} = 320 \text{ V}, V_{GS} = 0 \text{ V}, Tj = 125^{\circ}\text{C}$			10	
I _{GSS}	$V_{GS} = 30 \text{ V}, V_{DS} = 0 \text{ V}$			100	nA
R _{DS(ON)}	V _{GS} = 30 V, V _{DS} =0 V			-100	nA

Dynamic Characteristics					
Symbol	Test Conditions	Min	Тур.	Max.	Units
Q_g	VDS = 320 V,		25	33	nC
Q_{gs}	ID = 5.5 A,		5.0		
Q_{gd}	VGS =10 V		10		



N-Channel Enhancement Mode Power MOSFET

Dynamic Cha	Dynamic Characteristics					
Symbol	Test Conditions	Min	Тур.	Max.	Units	
$t_{\text{d(on)}}$			20	50	ns	
t _r	$V_{DS} = 200 \text{ V},$ $I_{D} = 5.5 \text{ A},$ $R_{G} = 25 \Omega$		50	110	ns	
t _{d(off)}			90	190	ns	
tf			55	120	ns	
C _{ISS}	V _{GS} = 0 V,		670	870	pF	
Coss	V _{DS} = 25 V,		95	125	pF	
C _{RSS}	f= 1MHz		16	21	pF	

Symbol	Test Conditions	Min	Typ.	Max.	Units
I _S				5.5	А
I _{SM}				22	Α
V_{SD}	I _S = 4.5 A , V _{GS} = 0 V			1.5	V
t _{rr}	L 55 A V		220		ns
Q _{rr}	$I_S = 5.5 \text{ A}, V_{GS} = 0 \text{ V diF/dt} = 100 \text{ A/}\mu\text{s}$		2		uC

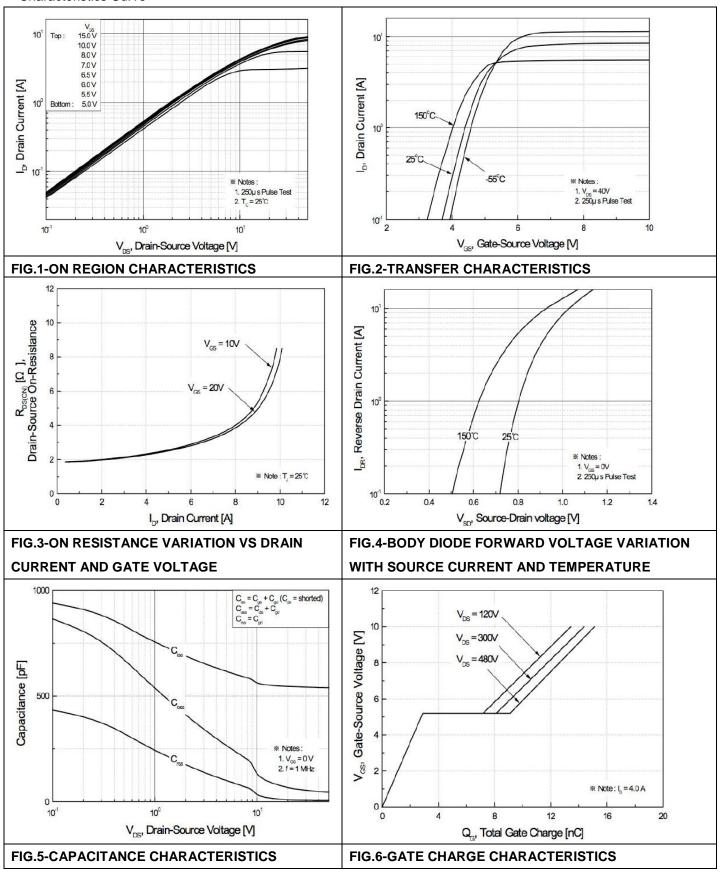
NOTE:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature
- 2. I_{AS} =5.5 A, V_{DD} =50V, R_{G} =25W, Starting TJ =25°C
- 3. $I_{SD} \le 5.5 \text{ A}$, di/dt $\le 300 \text{A/}\mu\text{s}$, VDD $\le \text{BVDSS}$, Starting TJ =25 °C
- 4. Pulse Test : Pulse Width ≤ 300µs, Duty Cycle ≤ 2%
- 5. Essentially Independent of Operating Temperature



N-Channel Enhancement Mode Power MOSFET

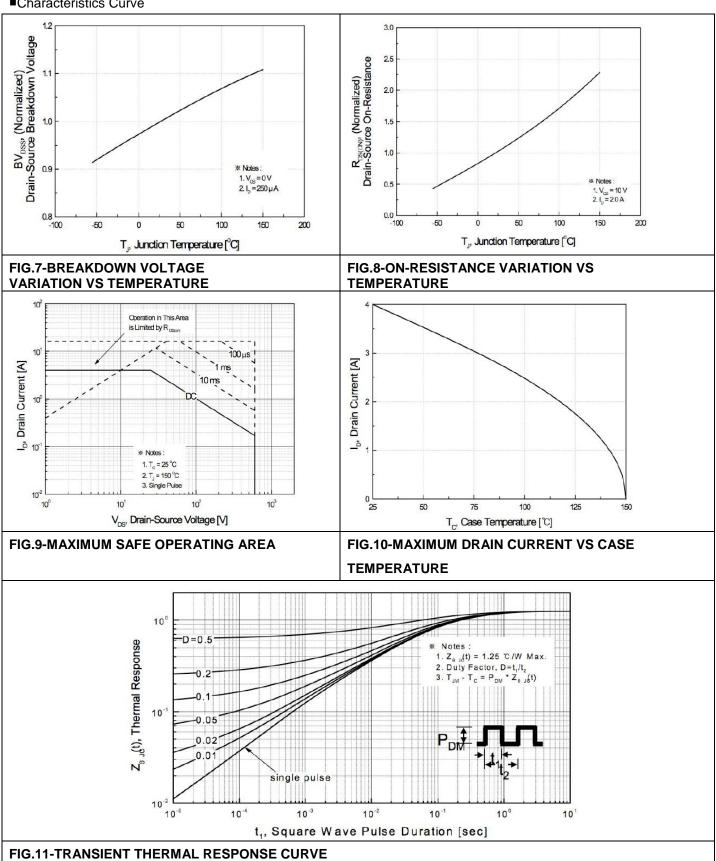
■Characteristics Curve





N-Channel Enhancement Mode Power MOSFET

■Characteristics Curve





N-Channel Enhancement Mode Power MOSFET

Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE. Bruckewell Technology Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Bruckewell"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product. Bruckewell makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Bruckewell disclaims

- (i) Any and all liability arising out of the application or use of any product.
- (ii) Any and all liability, including without limitation special, consequential or incidental damages.
- (iii) Any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Bruckewell's knowledge of typical requirements that are often placed on Bruckewell products in generic applications.

Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and/or specifications may vary in different applications and performance may vary over time.

Product specifications do not expand or otherwise modify Bruckewell's terms and conditions of purchase, including but not limited to the warranty expressed therein.